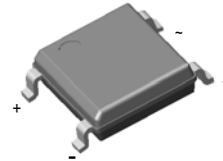




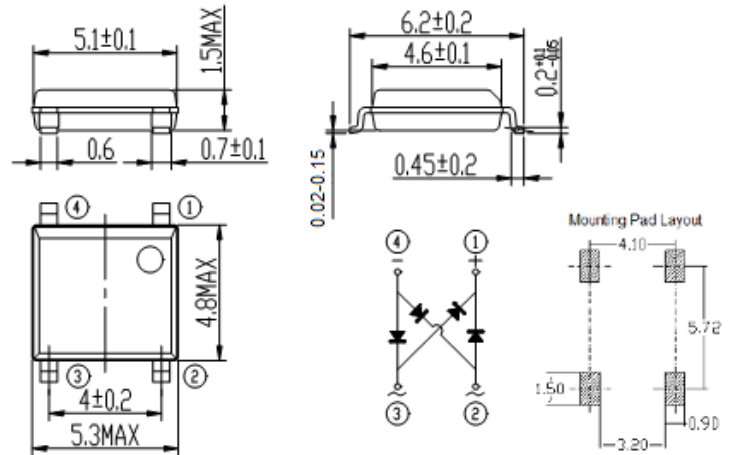
**Features**

- Low Profile: Typical height of 1.4mm
- Ideal for automated placement
- High surge current capability
- Solder Dip 260 , 10seconds



**Mechanical Data**

- Case:SOPA-4
- Epoxy meets UL-94V-0 Flammability rating
- Terminals:Matte tin plated leads, solderable per J-STD-002B and JESD22-B102D
- Polarity:As markde on body



**Maximum Ratings & Electrical Characteristics** Ratings at 25

ambient temperature unless otherwise specified.

Parameter	Symbol	LB2SA	LB4SA	LB6SA	LB8SA	LB10SA	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	200	400	600	800	1000	V
Maximum Average forward output rectified current	$I_{F(AV)}$					0.8	A
on glass-epoxy P.C.B						1.0	
on aluminum substrate							
Peak forward surge current 8.3 ms single sine-wave	$I_{FSM}$					25	A
superimposed on rated load (JEDEC Method)							
Rating for fusig (t<8.3ms)	$I^2t$					2.6	A <sup>2</sup> sec
Maximum instantaneous forward voltage drop	$V_F$					0.95	V
per diode at 0.4A							
Maximum DC reverse current at TA=25	$I_R$					5	μA
rated DC blocking voltage per leg TA=125						500	
Typical thermal resistance per leg (Note 1)	$R_{\theta JA}$					80	/W
	$R_{\theta JL}$					25	
Operating junction temperature range	$T_J$					-55 to +150	
Storage temperature range	$T_{STG}$					-55 to +150	

- Notes:** 1. Device mounted P.C.B with 0.47x0.47"(12mmx12mm) Copper Pads.  
2. JEDEC registered values



**RATINGS AND CHARACTERISTIC CURVES**

(TA=25 unless otherwise noted)

